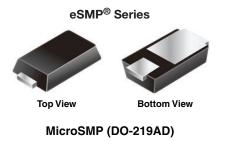
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Anode O Cathode

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	1 A				
V _R	100 V, 200 V				
V _F at I _F	0.72 V				
t _{rr} (typ.)	33 ns				
I _{FSM}	30 A				
T _J max.	175 °C				
Package	MicroSMP (DO-219AD)				
Circuit configuration	Single				

FEATURES

- Very low profile typical height of 1.0 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- · Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- For PFC, CRM snubber operation
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATION

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial and automotive applications.

MECHANICAL DATA

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per J-STD-002, meets JESD 201 class 2 whisker test **Polarity:** color band denotes cathode end

ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Dook repetitive reverse veltage	VS-1EQH01HM3	V		100	V			
Peak repetitive reverse voltage	VS-1EQH02HM3	V _{RRM}		200				
Average rectified forward current	I _{F(AV)}	T _M = 159 °C	1	А				
Non-repetitive peak surge current		I _{FSM}	$T_J = 25 \ ^{\circ}C$, 10 ms sine pulse	30	A			
Operating junction and storage temperatures		T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 $^{\circ}$ C unless otherwise specified)								
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage,	VS-1EQH01HM3	V _{BR} ,	L _ 100 HA	100	-	-		
blocking voltage	VS-1EQH02HM3	V _R	I _R = 100 μA	200			v	
Forward voltage		V _F	I _F = 1 A	-	0.88	0.97		
Forward voltage			I _F = 1 A, T _J = 150 °C	-	0.72	0.75		
Reverse leakage current			$V_{R} = V_{R}$ rated	-	-	1	μA	
		IR	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	25		
Junction capacitance		CT	V _R = 200 V	-	6	-	pF	

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1



HALOGEN

FREE



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 $^{\circ}$ C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			MAX.	UNITS	
		I _F = 1.0 A, dI _F /dt =	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s}, V_R = 30 \text{ V}$			-		
Reverse receiver time	+	$I_{\rm F} = 0.5 \text{ A}, I_{\rm R} = 1 \text{ A}$	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr} = 0.25 \text{ A}$			23	20	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	13	-	A nC	
		T _J = 125 °C		-	18	-		
Pools recovery oursent	1	T _J = 25 °C	$I_F = 1 A$	-	1.8	-		
Peak recovery current	IRRM	T _J = 125 °C	dI _F /dt = 200 A/µs V _R = 100 V	-	2.7	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	11	-		
		T _J = 125 °C		-	23	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and st	orage temperature range	T _J , T _{Stg}		-55	-	175	°C	
Thermal resistance, junction to mount		R _{thJM} ⁽¹⁾		-	16	20		
Thermal resistance, junction to ambient		R _{thJA}	Device mounted on FR4 PCB, 2 oz. standard footprint	-	160	-	°C/W	
Marking device VS-1EQH01HM3 VS-1EQH02HM3			Case style MicroSMP (DO-219AD)	1H1 1H2				
			Case sigle MicroSMF (DC-219AD)					

Note

⁽¹⁾ Thermal resistance junction to mount follows JEDEC[®] 51-14 transient dual interface test method (TDIM)

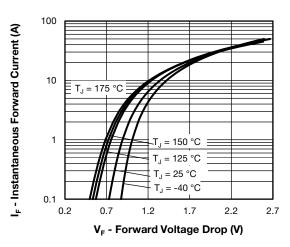


Fig. 1 - Typical Forward Voltage Drop Characteristics

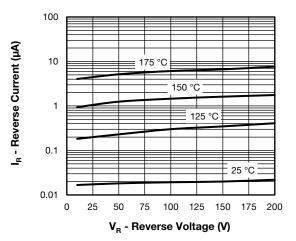


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



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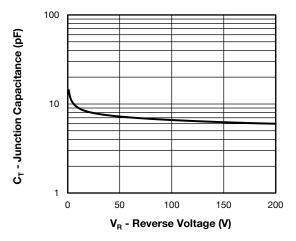


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

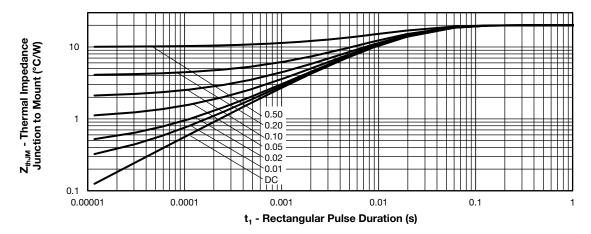
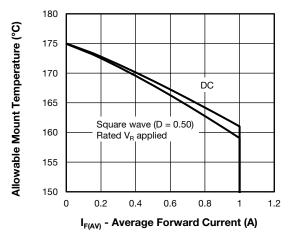
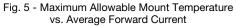


Fig. 4 - Maximum Transient Thermal Impedance, Junction to Mount

Average Power Loss (W)





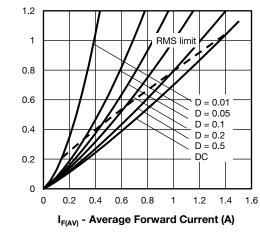


Fig. 6 - Forward Power Loss Characteristics

Note

Formula used: $T_M = T_J - (Pd + Pd_{REV}) \times R_{thJM}$; Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}/D$) (see fig. 5);

 Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

Revision: 28-Jan-2021

3

Document Number: 96563

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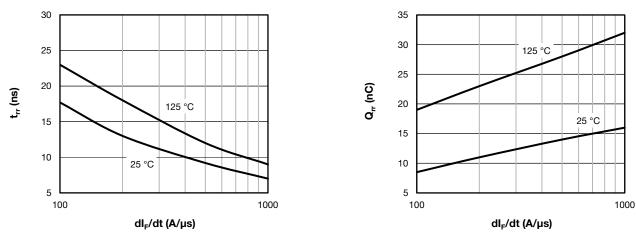


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

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Fig. 8 - Typical Stored Charge vs. dl_F/dt

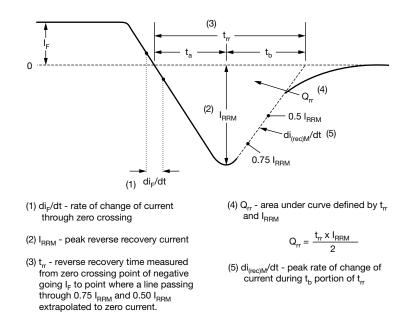
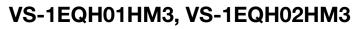


Fig. 9 - Reverse Recovery Waveform and Definitions



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ORDERING INFORMATION TABLE

Device code	VS-	1	Е	Q	н	02	н	М3	
		2	3	4	5	6	7	8	1
	브		•	niconduc		oduct			
				ng (1 = [·] iguratior	-				
	Ľ		single c	-					
	4	- Q =	MicroS	MP pac	kage				
	5	- Pro	cess typ	e,					
		H =	ultrafas	t recove	ery				
	6	- Vol	tage coo	de (02 =	200 V)				
	7	- H=	AEC-Q	101 qua	lified				
	8	- M3	= halog	en-free,	RoHS-0	complia	nt, and	termina	tions lead (Pl

ORDERING INFORMATION (Example)							
PREFERRED P/N	PREFERRED PACKAGE CODE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-1EQH01HM3/H	Н	4500	7" diameter plastic tape and reel				
VS-1EQH02HM3/H	Н	4500	7" diameter plastic tape and reel				

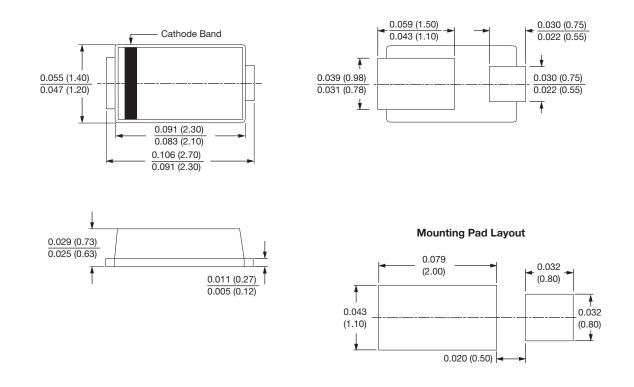
LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?96591					
Part marking information	www.vishay.com/doc?96590					
Packaging information	www.vishay.com/doc?88869					
SPICE model	www.vishay.com/doc?96594					



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MicroSMP (DO-219AD), FRED Pt®

DIMENSIONS in inches (millimeters)





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